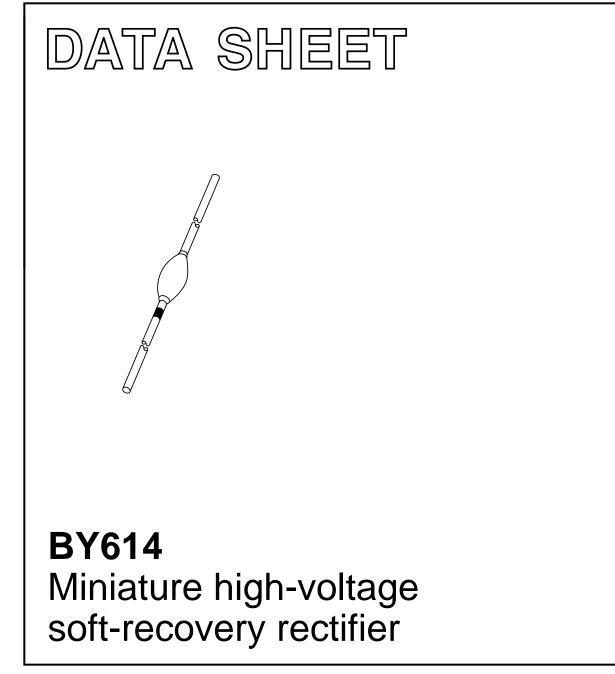
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of April 1992 File under Discrete Semiconductors, SC01 1996 May 24



## FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- · Excellent stability
- Soft-recovery switching characteristics
- Very compact construction.

## APPLICATIONS

• Miniature high-voltage assemblies such as voltage multipliers.

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RSM</sub>	non-repetitive peak reverse voltage		-	2200	V
V <sub>RRM</sub>	repetitive peak reverse voltage		-	2200	V
V <sub>RW</sub>	working reverse voltage		-	2000	V
V <sub>R</sub>	continuous reverse voltage		_	2000	V
I <sub>F(AV)</sub>	average forward current	averaged over any 20 ms period; PCB mounting (see Fig.5); T <sub>amb</sub> = 65 °C; see Fig.2; see also Fig.3	-	50	mA
I <sub>FRM</sub>	repetitive peak forward current		_	500	mA
I <sub>FSM</sub>	non-repetitive peak forward current	$t \le 10 \text{ ms; half sinewave;}$ $T_j = T_{j \text{ max}} \text{ prior to surge;}$ $V_R = V_{RWmax}$	-	1	A
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

#### DESCRIPTION

Miniature glass package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

The package is designed to be used in an insulating medium such as resin, oil or SF6 gas.

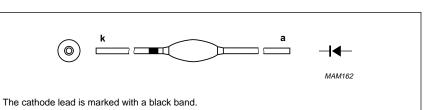


Fig.1 Simplified outline (SOD61H2) and symbol.

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## **ELECTRICAL CHARACTERISTICS**

 $T_i = 25 \ ^{\circ}C$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_F = 50 \text{ mA}; T_j = T_{j \text{ max}}; \text{ see Fig.4}$	_	_	6	V
I <sub>R</sub>	reverse current	$V_{R} = V_{RWmax}$ ; $T_{j} = 120 \text{ °C}$	_	_	3	μA
Qr	recovery charge	when switched from $I_F$ = 100 mA to $V_R \ge 100$ V and $dI_F/dt$ = $-200$ mA/µs; see Fig.6	_	_	1	nC
t <sub>f</sub>	fall time	when switched from $I_F$ = 100 mA to $V_R \ge 100$ V and $dI_F/dt$ = -200 mA/µs; see Fig.6	100	_	-	ns
t <sub>rr</sub>	reverse recovery time	when switched from I <sub>F</sub> = 100 mA to $V_R \ge 100$ V and dI <sub>F</sub> /dt = -200 mA/µs; see Fig.6	_	-	300	ns
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0 V; f = 1 MHz	_	2	_	pF

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	100	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	155	K/W

### Note

1. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper ≥40 μm, see Fig.5. For more information please refer to the *"General Part of Handbook SC01"*.

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**GRAPHICAL DATA** 

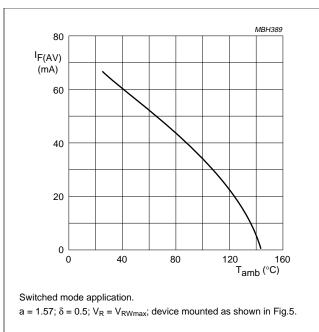
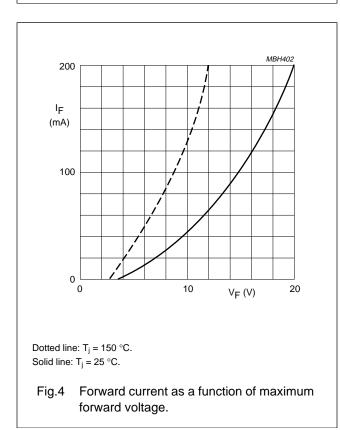
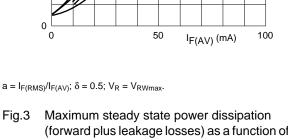


Fig.2 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).





a = 3 2.5 2 1.57 1.42

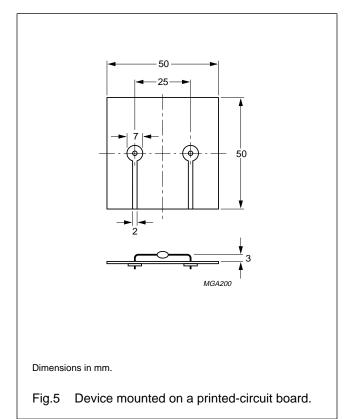
1000

Ρ

(mW)

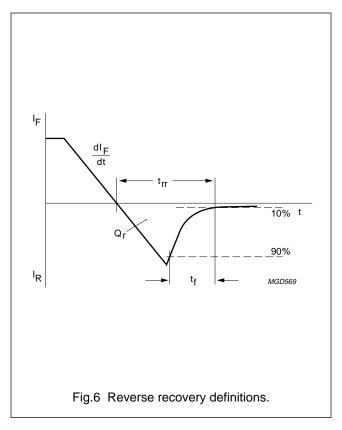
500

(forward plus leakage losses) as a function of average forward current.



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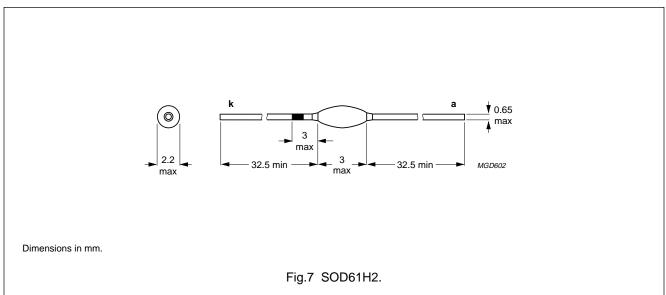
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Product specification

#### Product specification

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## PACKAGE OUTLINE



## DEFINITIONS

Data Sheet Status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
more of the limiting values r of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or nay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification imiting values for extended periods may affect device reliability.	
Application information		

Where application information is given, it is advisory and does not form part of the specification.

## LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.